



S/N 10/052089

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Krishna Seshan et al. Examiner: Kiley Shawn Stoner
Serial No.: 10/052089 Group Art Unit: 1725
Filed: January 16, 2002 Docket No.: 884.659US1
Title: A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6
Assignee: Intel Corporation Customer No.: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant has reviewed the Office Action mailed on May 29, 2003. Please amend the above-identified patent application as follows.

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